PRODUCT / PROCESS CHANGE NOTIFICATION

| 1. PCN basic data | | | |
|----------------------|--|--|--|
| 1.1 Company | | STMicroelectronics International N.V | |
| 1.2 PCN No. | | ADG/19/11528 | |
| 1.3 Title of PCN | | Mold compound replacement for TO247 | |
| 1.4 Product Category | | TM8050H-12W, STPSxxx, STPSCxxx, STBRxxx, STTHxxx series. | |
| 1.5 Issue date | | 2019-05-06 | |

| 2. PCN Team | |
|---------------------------|----------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | MARSHALL DAVE |
| 2.1.2 Phone | |
| 2.1.3 Email | dave.marshall@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Richard RENARD |
| 2.1.2 Marketing Manager | Philippe LEGER |
| 2.1.3 Quality Manager | Jean-Paul REBRASSE |

| 3. Change | | |
|--------------|--|-----------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Materials | New direct material part number (same supplier, different supplier or new supplier), Mold compound | ST assy site in China (STS) |

| 4. Description of change | | |
|---|---|---|
| | Old | New |
| 4.1 Description | Samsung SDI product termination of the following references of molding compound for through hole packages | Replacement of current mold compounds with alternative material. ST is already proceeding with new resins evaluation and qualification, to guarantee adequate products continuity. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | no | |

| 5. Reason / motivation for change | |
|-----------------------------------|---|
| 5.1 Motivation | Product discontinuance from current supplier. |
| 5.2 Customer Benefit | SERVICE CONTINUITY |

| 6. Marking of parts / traceability of change | |
|--|-------------------------------------|
| 6.1 Description | internal codification and QA number |

| 7. Timing / schedule | | |
|-------------------------------------|--------------|--|
| 7.1 Date of qualification results | 2019-08-29 | |
| 7.2 Intended start of delivery | 2019-09-13 | |
| 7.3 Qualification sample available? | Upon Request | |

| 8. Qualification / Validation | | | |
|---|-------------|---------------|--|
| 8.1 Description | | | |
| 8.2 Qualification report and qualification results | In progress | Issue Date | |

11528 Public product.pdf 11528 PCN-TO247 industrial draft.pdf

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| 9803815 | STTH6003CW | |
| | STTH6004W | |
| 2723338 | STBR3012W | |
| 2723340 | STBR6012W | |
| 2980901 | STTH60RQ06W | |
| 2579644 | TM8050H-8W | |

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